Apparatus and Method for Handling Lead-Frame.

Abstract

An apparatus for handling lead frames for use in the manufacture of IC Chips, which includes a means to place the said lead frame to a first position of an input track, an input track including a pair of spaced, parallel rails having opposed generally, having outwardly facing, L-shaped portions defining a pair of co-planer surfaces for supporting edge portions of the lead frames and a pair of upright surfaces forming a guide for the leads frame as it is positioned on the supporting surfaces, characterised in that the rails are mounted for contra rotation between the lead frames supporting position and a lead frame holding position in which the edges of the lead frame are received in the apex of the angle between the arms of the 'L'-shaped portions. A method for handling lead frames using the apparatus of the present invention is also disclosed.

Figure 1